

April 2002

High Speed Precision Sample and Hold Amplifier

Features

- This Circuit is Processed in Accordance to MIL-STD-883 and is Fully Conformant Under the Provisions of Paragraph 1.2.1.

- Internal Hold Capacitor
- · Fully Differential Input
- TTL Compatible

Applications

- High Bandwidth Precision Data Acquisition Systems
- Inertial Navigation and Guidance Systems
- Ultrasonics
- SONAR / RADAR
- Digital to Analog Converter Deglitcher

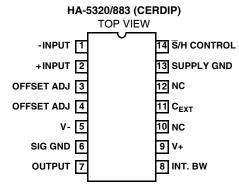
Description

The HA-5320/883 was designed for use in precision, high speed data acquisition systems.

The circuit consists of an input transconductance amplifier capable of providing large amounts of charging current, a low leakage analog switch, and an output integrating amplifier. The analog switch sees virtual ground as its load; therefore, charge injection on the hold capacitor is constant over the entire input/output voltage range. The pedestal voltage resulting from this charge injection can be adjusted to zero by use of the offset adjust inputs. The device includes a hold capacitor. However, if improved droop rate is required at the expense of acquisition time, additional hold capacitance may be added externally.

This monolithic device is manufactured using the Intersil Dielectric Isolation Process, minimizing stray capacitance and eliminating SCR's. This allows higher speed and latch-free operation. For further information, please see Application Note AN538.

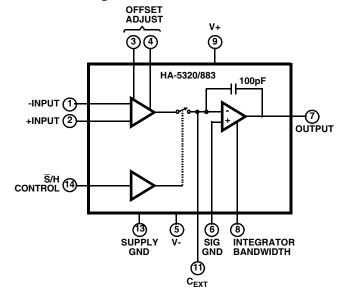
Pinout



Ordering Information

PART NUMBER	TEMPERATURE RANGE	PACKAGE
HA1-5320/883	-55°C to +125°C	14 Lead CerDIP

Functional Diagram



Absolute Maximum Ratings Thermal Information Voltage Between V+ and V- Terminals 40V Thermal Resistance θ_{JA} θ_{JC} 75°C/W 20°C/W Differential Input Voltage 24V Digital Input Voltage (S/H Pin) +8V, -15V Package Power Dissipation at +75°C Storage Temperature Range -65°C to +150°C Package Power Dissipation Derating Factor Above +75°C Junction Temperature.....+175°C CerDip Package 15mW/°C Lead Temperature (Soldering 10s). +300°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

 θ_{JA} is measured with the component mounted on a low effective thermal conductivity test board in free air. See Tech Brief TB379 for details.

Operating Conditions

Operating Temperature Range -55° C \leq T _A \leq +125°C	Logic Level Low (V _{IL})
Operating Supply Voltage (±V _S)	Logic Level High (V _{IH})
Analog Input Voltage	

TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS

Device Tested at: $V_{+} = +15V$; $V_{-} = -15V$; $V_{L} = 0.8V$ (Sample); $V_{IH} = 2.0V$ (Hold); $C_{H} = Internal = 100pF$; Signal GND = Supply GND, Unless Otherwise Specified

			GROUP A		LIMITS		
PARAMETERS	SYMBOL	CONDITIONS	SUBGROUP			MAX	UNITS
Input Offset Voltage	V_{IO}		1	+25°C	-1	+1	mV
			2, 3	+125°C, -55°C	-2	+ 2	mV
Input Bias Current	+l _B		1	+25°C	-200	+200	nA
			2, 3	+125°C, -55°C	-200	+200	nA
	-I _B		1	+25°C	-200	+200	nA
			2, 3	+125°C, -55°C	-200	+200	nA
Input Offset Current	I _{IO}		1	+25°C	-100	+100	nA
			2, 3	+125°C, -55°C	-100	+100	nA
Open Loop Voltage Gain	+A _{VS}	$R_L = 1k\Omega$, $V_{OUT} = +10V$	1	+25°C	120	-	dB
			2, 3	+125°C, -55°C	110	-	dB
	-A _{VS}	$R_L = 1k\Omega$, $V_{OUT} = -10V$	1	+25°C	120	-	dB
			2, 3	+125°C, -55°C	110	-	dB
Common Mode	+CMRR	V+ = 10V, V- = -20V,	1	+25°C	80	-	dB
Rejection Ratio		$V_{OUT} = -5V, V_{S/H} = -4.2V, V_{GND} = -5V$	2, 3	+125°C, -55°C	80	-	dB
	-CMRR	V+ = 20V, V- = -10V,	1	+25°C	80	-	dB
		$V_{OUT} = +5V, V_{S/H} = 5.8V, V_{GND} = +5V$	2, 3	+125°C, -55°C	80	-	dB
Output Current	+l ₀	V _{OUT} = +10V	1	+25°C	10	-	mA
			2, 3	+125°C, -55°C	10	-	mA
	-l _O	V _{OUT} = -10V	1	+25°C	-10	-	mA
			2, 3	+125°C, -55°C	-10	-	mA

TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS (Continued)

Device Tested at: $V_{+} = +15V$; $V_{-} = -15V$; $V_{IL} = 0.8V$ (Sample); $V_{IH} = 2.0V$ (Hold); $C_{H} = Internal = 100pF$; Signal GND = Supply GND, Unless Otherwise Specified

	GROUP		GROUP A		LIMITS		
PARAMETERS	SYMBOL	CONDITIONS	SUBGROUP	TEMPERATURE	MIN	MAX	UNITS
Output Voltage Swing	+V _{OP}	$R_L = 1k\Omega$	1	+25°C	10	-	V
			2, 3	+125°C, -55°C	10	-	٧
	-V _{OP}	$R_L = 1k\Omega$	1	+25°C	=	-10	٧
			2, 3	+125°C, -55°C	-	-10	٧
Power Supply Current	+I _{CC}	V _{OUT} = 0V, I _{OUT} = 0mA	1	+25°C	-	13	mA
			2, 3	+125°C, -55°C	=	13	mA
	-I _{CC}	V _{OUT} = 0V, I _{OUT} = 0mA	1	+25°C	-13	-	mA
			2, 3	+125°C, -55°C	-13	-	mA
Power Supply Rejection	+PSRR	V+ = 14.5V, 15.5V	1	+25°C	80	-	dB
Ratio	V- = -15V, -15V	2, 3	+125°C, -55°C	80	-	dB	
	-PSRR	V+ = +15V, +15V,	1	+25°C	65	-	dB
		V- = -14.5V, -15.5V	2, 3	+125°C, -55°C	65	-	dB
Digital Input Current	I _{INL}	V _{IN} = 0V	1	+25°C	-	4	μΑ
			2, 3	+125°C, -55°C	-	10	μΑ
	I _{INH}	V _{IN} = 5V	1	+25°C	-	0.1	μΑ
			2, 3	+125°C, -55°C	-	0.1	μΑ
Digital Input Voltage	V _{IL}		1	+25°C	-	0.8	٧
			2, 3	+125°C, -55°C	-	0.8	٧
	V _{IH}		1	+25°C	2.0	-	٧
			2, 3	+125°C, -55°C	2.0	-	٧
Output Voltage Droop Rate	V _D	V _{OUT} = 0V	2	+125°C	-	100	μV/μs

NOTE:

TABLE 2. AC ELECTRICAL PERFORMANCE CHARACTERISTICS

Table 2 Intentionally Left Blank. See AC Specifications in Table 3.

^{1.} Internal power dissipation may limit output current below 20mA.

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS

					LIMITS		
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX	UNITS
Hold Mode Feedthrough	V_{HMF}	V _{IN} = 10V _{P-P} , 100kHz	1	+25°C	=	3	mV
Hold Step Error	V _{ERROR}	$V_{IH} = 3.5V$, $V_{IL} = 0V$, $T_{RISE} (V_{IL} \text{ to } V_{IH}) = 10 \text{ns}$	1	+25°C	-11	11	mV
Sample Mode Noise Voltage	E _{N(SAM} - PLE)	DC to 10MHz, $V_{S/H} = 0V$, $R_{LOAD} = 2k\Omega$	1	+25°C	-	200	μV _{RMS}
Hold Mode Noise Voltage	E _{N(HOLD)}	DC to 10MHz, $V_{S/H} = 5V$, $R_{LOAD} = 2k\Omega$	1	+25°C	-	200	μV _{RMS}
Input Capacitance	C _{IN}	V _{S/H} = 0V	1	+25°C	-	5	pF
Input Resistance	R _{IN}	V _{S/H} = 0V, Delta V _{IN} = 20V	1	+25°C	1	-	МΩ
Slew Rate	+SR	C_L = 50pF, R_L = 2k Ω , V_{OUT} = -5V to +5V Step 10%, 90% pts	1	+25°C	30	-	V/µs
	-SR	C_L = 50pF, R_L = 2k Ω , V_{OUT} = +5V to -5V Step 10%, 90% pts	1	+25°C	30	-	V/μs
Rise and Fall Times	T _R	C_L = 50pF, R_L = 2k Ω , V_{OUT} = 0V to +200mV Step 10%, 90% pts	1	+25°C	-	150	ns
	T _F	C_L = 50pF, R_L = 2k Ω , V_{OUT} = 0V to -200mV Step 10%, 90% pts	1	+25°C	-	150	ns
Overshoot	+OS	$C_L = 50 pF$, $R_L = 2 k\Omega$, $V_{OUT} = 0 V$ to +200mV Step	1	+25°C	-	25	%
	-OS	C_L = 50pF, R_L = 2k Ω , V_{OUT} = 0V to -200mV Step	1	+25°C	-	25	%
0.1% Acquisition Time	T _{ACQ} 0.1%	$C_L = 50 pF$, $R_L = 2 k\Omega$, $V_{OUT} = 0 V$ to 10 V Step	1	+25°C	-	1.2	μ\$

NOTE:

TABLE 4. ELECTRICAL TEST REQUIREMENTS

MIL-STD-883 TEST REQUIREMENTS	SUBGROUPS (SEE TABLE 1)
Interim Electrical Parameters (Pre Burn-In)	-
Final Electrical Test Parameters	1(Note 1), 2, 3
Group A Test Requirements	1, 2, 3
Groups C and D Endpoints	1

NOTE:

1. PDA applies to Subgroup 1 only. No other subgroups are included in PDA.

^{1.} The parameters listed in this table are controlled via design or process parameters and are not directly tested. These parameters are characterized upon initial design release and upon design changes which would affect these characteristics.

Die Characteristics

DIE DIMENSIONS:

92 x 152 x 19 \pm 1mils

METALLIZATION:

Type: Al, 1% Cu Thickness: 16kÅ ± 2kÅ

GLASSIVATION:

Type: Nitride (Si_3N_4) over Silox (SiO_2 , 5% Phos) Silox Thickness: $12k\mathring{A} \pm 2k\mathring{A}$ Nitride Thickness: $3.5k\mathring{A} \pm 1.5k\mathring{A}$

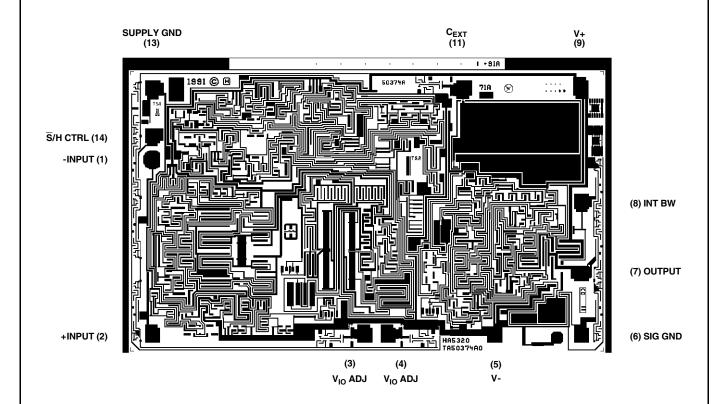
WORST CASE CURRENT DENSITY:

1.742 x 10⁵ A/cm²

TRANSISTOR COUNT: 184 SUBSTRATE POTENTIAL: V-

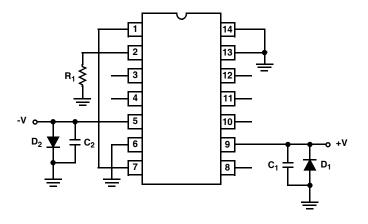
Metallization Mask Layout

HA-5320/883



Burn-In Circuits

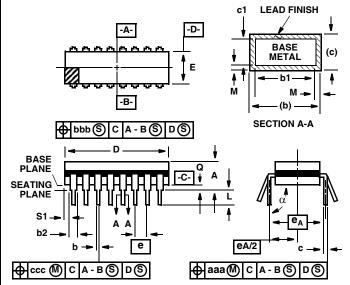
HA-5320/883 DIP BURN-IN/LIFE TEST CIRCUIT



NOTES:

- 1. $R_1 = 100k\Omega$, 5%, (per socket).
- 2. C_1 , $C_2 = 0.01 \mu F$ minimum per socket or $0.1 \mu F$ minimum per row.
- 3. D_1 , $D_2 = 1N4002$ or equivalent (per board).
- 4. $+V = +15.5V \pm 0.5V$, $-V = -15.5V \pm 0.5V$.

Packaging



NOTES:

- Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.
- The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
- Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness.
- Corner leads (1, N, N/2, and N/2+1) may be configured with a partial lead paddle. For this configuration dimension b3 replaces dimension b1.
- 5. This dimension allows for off-center lid, meniscus, and glass
- 6. Dimension Q shall be measured from the seating plane to the base plane.
- 7. Measure dimension S1 at all four corners.
- 8. N is the maximum number of terminal positions.
- 9. Dimensioning and tolerancing per ANSI Y14.5M 1982.
- 10. Controlling Dimension: Inch.
- 11. Materials: Compliant to MIL-I-38535.

F14.3 MIL-STD-1835 GDIP1-T14 (D-1, CONFIGURATION A) 14 LEAD DUAL-IN-LINE FRIT-SEAL CERAMIC PACKAGE

	INC	HES	MILLIMETERS		
SYMBOL	MIN	MAX	MIN	MAX	NOTES
Α	-	0.200	-	5.08	-
b	0.014	0.026	0.36	0.66	2
b1	0.014	0.023	0.36	0.58	3
b2	0.045	0.065	1.14	1.65	-
b3	0.023	0.045	0.58	1.14	4
С	0.008	0.018	0.20	0.46	2
c1	0.008	0.015	0.20	0.38	3
D	-	0.785	-	19.94	5
Е	0.220	0.310	5.59	7.87	5
е	0.100	BSC	2.54 BSC		-
eA	0.300	BSC	7.62 BSC		-
eA/2	0.150	BSC	3.81	BSC	-
L	0.125	0.200	3.18	5.08	-
Q	0.015	0.060	0.38	1.52	6
S1	0.005	-	0.13	-	7
S2	0.005	-	0.13	-	-
α	90°	105°	90°	105°	-
aaa	-	0.015	=	0.38	-
bbb	=	0.030	=	0.76	-
ccc	=	0.010	=	0.25	-
М	-	0.0015	-	0.038	2
N	1	4	14		8



HA-5320

DESIGN INFORMATION

May 2002

High Speed Precision Sample and Hold Amplifier

The information contained in this section has been developed through characterization by Intersil Semiconductor and is for use as application and design information only. No guarantee is implied.

Applying the HA-5320

The HA-5320 has the uncommitted differential inputs of an op amp, allowing the Sample and Hold function to be combined with many conventional op amp circuits. See the Intersil Application Note 517 for a collection of circuit ideas.

Layout

A printed circuit board with ground plane is recommended for best performance. Bypass capacitors (0.01 to $0.1\mu F$, ceramic) should be provided from each power supply terminal to the Supply Ground terminal on pin 13.

The ideal ground connections are pin 6 (SIG. Ground) directly to the system Signal Ground, and pin 13 (Supply Ground) directly to the system Supply Common.

Hold Capacitor

The HA-5320 includes a 100pF MOS hold capacitor, sufficient for most high speed applications (the Electrical Specifications section is based on this internal capacitor). Additional capacitance may be added between pins 7 and 11. This external hold capacitance will reduce droop rate at the expense of acquisition time, and provide other trade-offs as shown in the Performance Curves.

If an external hold capacitor C_{EXT} is used, then a noise band- width capacitor of value $0.1C_{\text{EXT}}$ should be connected from pin 8 to ground. Exact value and type are not critical.

The hold capacitor C_{EXT} should have high insulation resistance and low dielectric absorption, to minimize droop

errors. Polystyrene dielectric is a good choice for operating temperatures up to +85°C. Teflon® and glass dielectrics offer good performance to +125°C and above.

The hold capacitor terminal (pin 11) remains at virtual ground potential. Any PC connection to this terminal should be kept short and "guarded" by the ground plane, since nearby signal lines or power supply voltages will introduce errors due to drift current.

®Teflon is a registered Trademark of Dupont Corporation.

Applications

Figure 1 shows the HA-5320 connected as a unity gain non-inverting amplifier – its most widely used configuration. As an input device for a fast successive – approximation A/D converter, it offers very high throughput rate for a monolithic IC sample/hold amplifier. Also, the hold step error is adjustable to zero using the Offset Adjust potentiometer, to deliver a 12-bit accurate output from the converter.

The application may call for an external hold capacitor C_{EXT} as shown. As mentioned earlier, $0.1C_{\text{EXT}}$ is then recommended at pin 8 to reduce output noise in the Hold mode.

The HA-5320 output circuit does not include short circuit protection, and consequently its output impedance remains low at high frequencies. Thus, the step changes in load current which occur during an A/D conversion are absorbed at the S/H output with minimum voltage error. A momentary short circuit to ground is permissible, but the output is not designed to tolerate a short of indefinite duration.

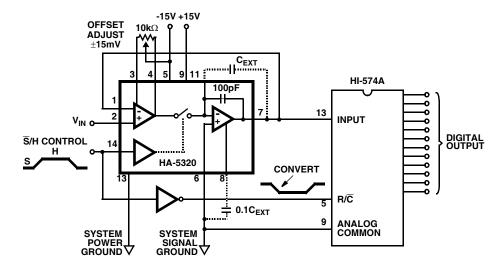


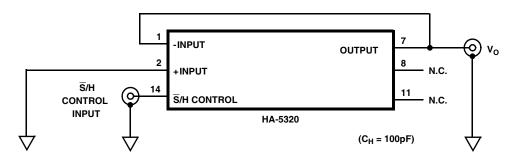
FIGURE 1. TYPICAL HA-5320/883 CONNECTIONS; NONINVERTING UNITY GAIN MODE

DESIGN INFORMATION (Continued)

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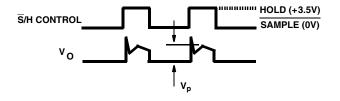
Test Circuits

CHARGE TRANSFER AND DRIFT CURRENT



CHARGE TRANSFER TEST

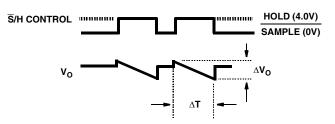
1. Observe the "hold step" voltage V_p :



2. Compute charge transfer: $Q = V_pC_H$

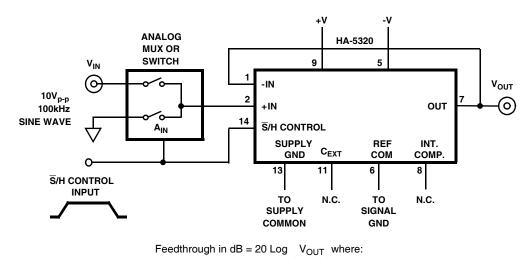
DRIFT CURRENT TEST

1. Observe the voltage "droop", $\Delta V_O/\Delta T$:



2. Measure the slope of the output during hold, $\Delta V_O/\!\Delta T,$ and compute drift current: I_D = C_H $\Delta V_O/\!\Delta T.$

HOLD MODE FEED THROUGH ATTENUATION



Spec Number **511096-883**

 $V_{OUT} = Volts_{p-p}$, Hold Mode,

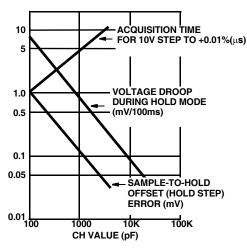
 $V_{IN} = Volts_{p-p}$.

DESIGN INFORMATION (Continued)

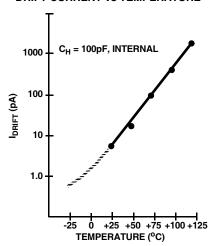
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Performance Curves $V_{SUPPLY} = \pm 15VDC$

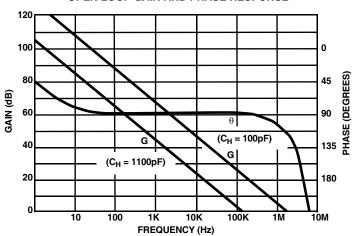
TYPICAL SAMPLE AND HOLD PERFORMANCE AS FUNCTION OF HOLDING CAPACITOR



DRIFT CURRENT vs TEMPERATURE

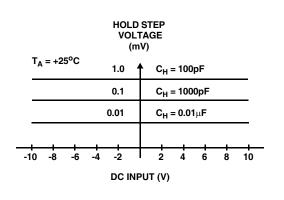


OPEN LOOP GAIN AND PHASE RESPONSE

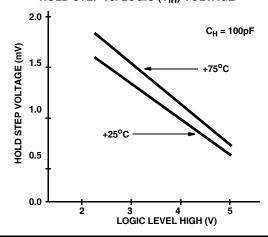


TYPICAL SAMPLE-TO-HOLD OFFSET (HOLD STEP) ERROR

HOLD STEP vs. INPUT VOLTAGE



HOLD STEP vs. LOGIC (VIH) VOLTAGE



DESIGN INFORMATION (Continued)

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Glossary of Terms

Acquisition Time

The time required following a "sample" command, for the output to reach its final value within $\pm 0.1\%$ or $\pm 0.01\%$. This is the minimum sample time required to obtain a given accuracy, and includes switch delay time, slewing time and settling time.

Charge Transfer

The small charge transferred to the holding capacitor from the inter-electrode capacitance of the switch when the unit is switched to the HOLD mode. Charge transfer is directly proportional to sample-to-hold offset pedestal error, where:

Charge Transfer (pC) = C_H (pF) x Offset Error (V)

Aperture Time

The time required for the sample-and-hold switch to open, independent of delays through the switch driver and input amplifier circuitry. The switch opening time is the interval between the conditions of 10% open and 90% open.

Hold Step Error

Hold Step Error is the output error due to Charge Transfer (see above). It may be calculated from Charge Transfer, using the following relationship:

See Performance Curves.

Effective Aperture Delay Time (EADT)

The difference between propagation time from the analog input to S/H switch, and digital delay time between the Hold command and opening of the switch.

EADT may be positive, negative or zero. If zero, the \overline{S}/H amplifier will output a voltage equal to V_{IN} at the instant the Hold command was received. For negative EADT, the output in Hold (exclusive of pedestal and droop errors) will correspond to a value of V_{IN} that occurred before the Hold command.

Aperture Uncertainty

The range of variation in Effective Aperture Delay Time. Aperture Uncertainty (also called Aperture Delay Uncertainty, Aperture Time Jitter, etc.) sets a limit on the accuracy with which a waveform can be reconstructed from sample data.

Drift Current

The net leakage current from the hold capacitor during the hold mode. Drift current can be calculated from the droop rate using the formula:

$$I_D (pA) = C_H (pF) \times \Delta V$$
 ΔT
 ΔT

TYPICAL PERFORMANCE CHARACTERISTICS

PARAMETER	CONDITIONS	TEMPERATURE	TYP	UNITS
Input Voltage Range		Full	±10	V
Offset Voltage Drift		Full	5	μV/°C
Gain Bandwidth Product (C _H = 100pF)	$Av = +1, V_O = 200 \text{mV}_{P-P}, R_L = 2K, C_L = 50 \text{pF}$	+25°C	2	MHz
Gain Bandwidth Product (C _H = 1000pF)	$Av = +1, V_O = 200 \text{mV}_{P-P}, R_L = 2K, C_L = 50 \text{pF}$	+25°C	0.18	MHz
Full Power Bandwidth	$V_O = 20V_{P-P}, R_L = 2K, C_L = 50pF$	+25°C	600	kHz
Output Resistance (Hold Mode)		+25°C	1.0	Ω
0.1% Acquisition Time	$V_{O} = 10V \text{ Step}, R_{L} = 2K, C_{L} = 50pF$	+25°C	0.8	μS
0.01% Acquisition Time	$V_{O} = 10V \text{ Step}, R_{L} = 2K, C_{L} = 50pF$	+25°C	1.0	μs
Effective Aperture Delay Time		+25°C	-25	ns
Aperture Uncertainty		+25°C	0.3	ns
0.01% Hold Mode Settling Time		+25°C	165	ns

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